

1-layer FPC; PI (polyimide), with adhesive; 35µm Cu; total thickness: ~0,13mm

Additional Stiffener (not shown in stack-up): None

Stack-up code: F25A25C35A20B25A0C0A0C0A0B0A0C0A0C0A0B0A0C0A0N0

Layer	Description	Stack-up	Thickness	Type
	Cover Lay, yellow		25,0 µm	Polyimide
	Adhesive		25,0 µm	Epoxy
L1	Copper		35,0 µm	Cu RA
	Adhesive		20,0 µm	Epoxy
	Base Film		25,0 µm	Polyimide
total thickness:			0,130 mm	
tolerance			10%	
maximum thickness			0,143 mm	
minimum thickness			0,117 mm	

2-layer FPC; PI (polyimide), with adhesive; 28µm Cu; total thickness: ~0,173mm

Additional Stiffener (not shown in stack-up): None

Stack-up code: F13A13C28A20B25A20C28A0C0A0B0A0C0A0C0A0B0A0C0A13F13

Layer	Description	Stack-up	Thickness	Type
	Cover Lay, yellow		13,0 µm	Polyimide
	Adhesive		13,0 µm	Epoxy
L1	Copper		28,0 µm	Cu RA
	Adhesive		20,0 µm	Epoxy
	Base Film		25,0 µm	Polyimide
	Adhesive		20,0 µm	Epoxy
L2	Copper		28,0 µm	Cu RA
	Adhesive		13,0 µm	Epoxy
	Cover Lay, yellow		13,0 µm	Polyimide
			total thickness:	0,173 mm
			tolerance	10%
			maximum thickness	0,190 mm
			minimum thickness	0,156 mm

4-layer FPC; PI (polyimide), with adhesive; 28µm Cu; total thickness: ~0,294mm

Additional Stiffener (not shown in stack-up): None

Stack-up code: F13A13C28A20B25A20C18A20C18A20B25A20C28A0C0A0B0A0C0A13F13

Layer	Description	Stack-up	Thickness	Type
	Cover Lay, yellow		13,0 µm	Polyimide
	Adhesive		13,0 µm	Epoxy
L1	Copper		28,0 µm	Cu RA
	Adhesive		20,0 µm	Epoxy
	Base Film		25,0 µm	Polyimide
	Adhesive		20,0 µm	Epoxy
L2	Copper		18,0 µm	Cu RA
	Adhesive		20,0 µm	Epoxy
L3	Copper		18,0 µm	Cu RA
	Adhesive		20,0 µm	Epoxy
	Base Film		25,0 µm	Polyimide
	Adhesive		20,0 µm	Epoxy
L4	Copper		28,0 µm	Cu RA
	Adhesive		13,0 µm	Epoxy
	Cover Lay, yellow		13,0 µm	Polyimide

total thickness:	0,294 mm
tolerance	10%
maximum thickness	0,323 mm
minimum thickness	0,265 mm